

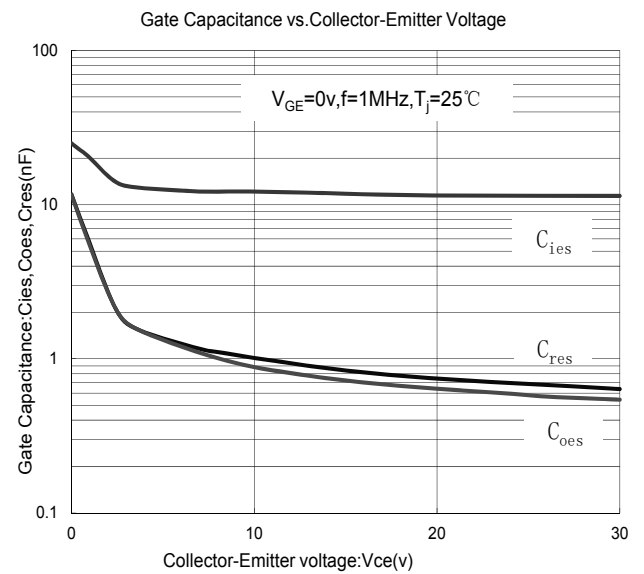
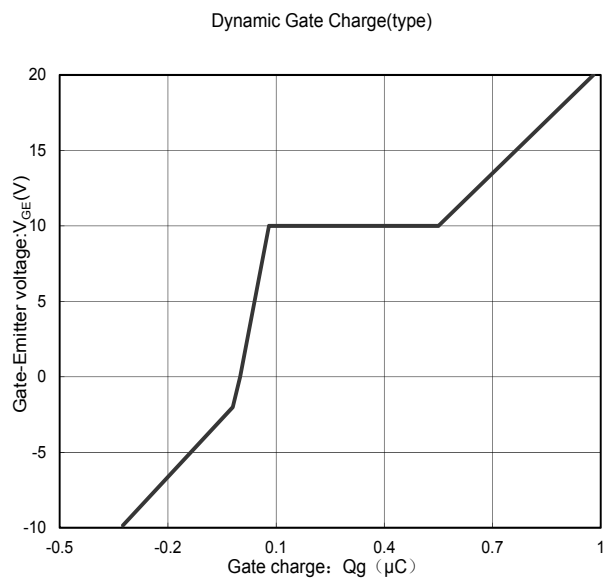
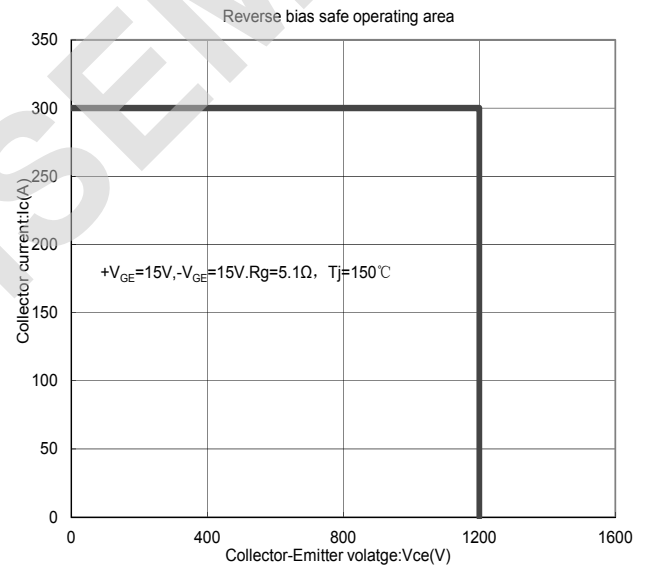
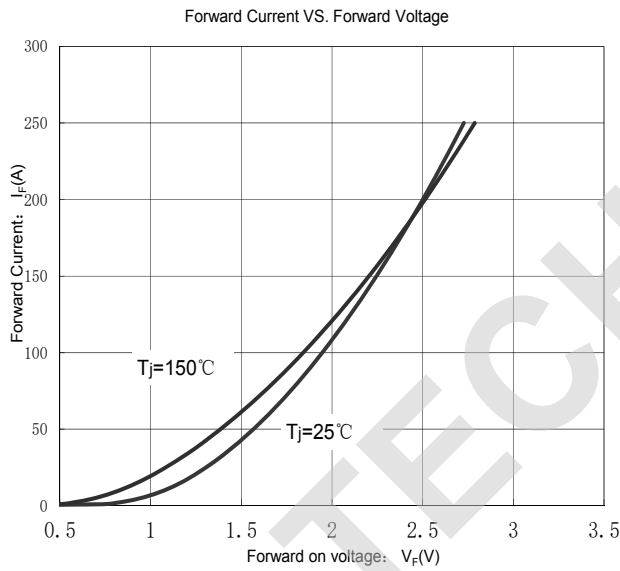
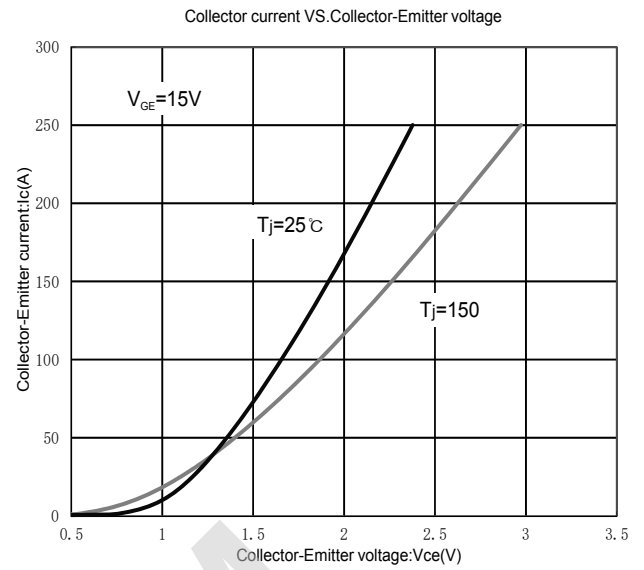
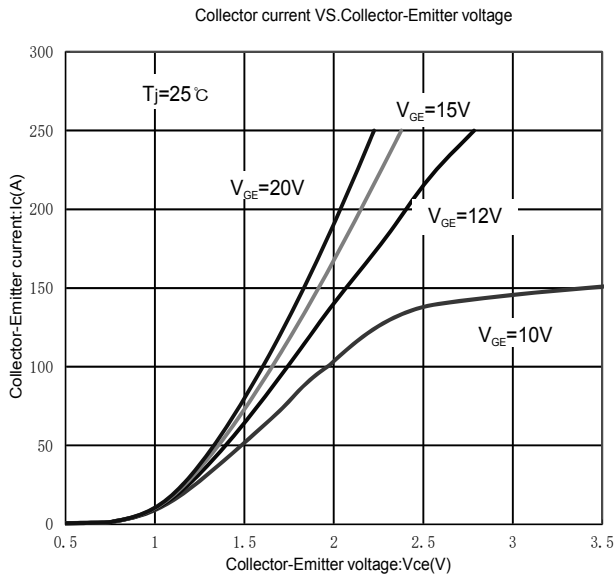
Features:

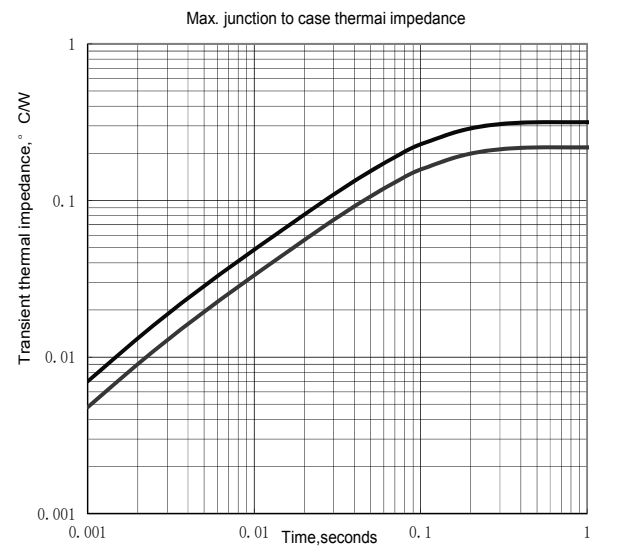
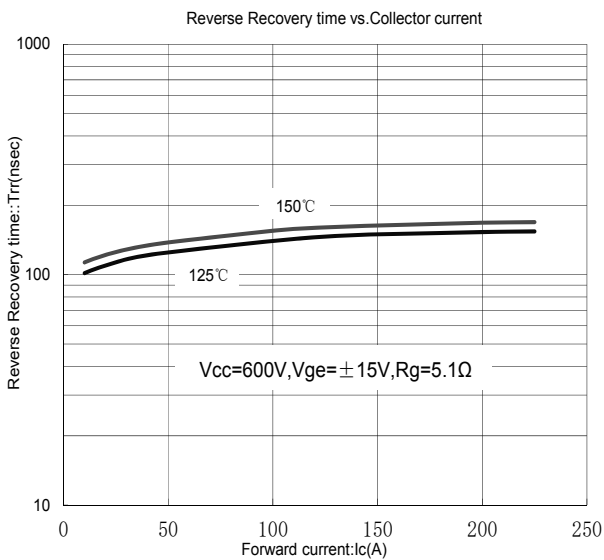
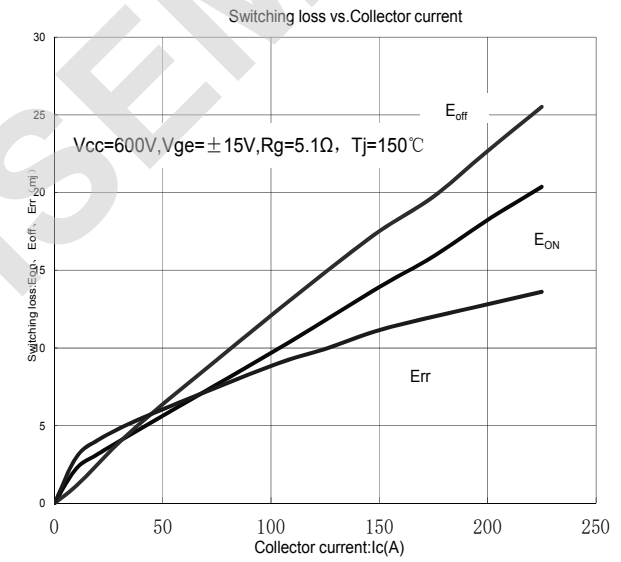
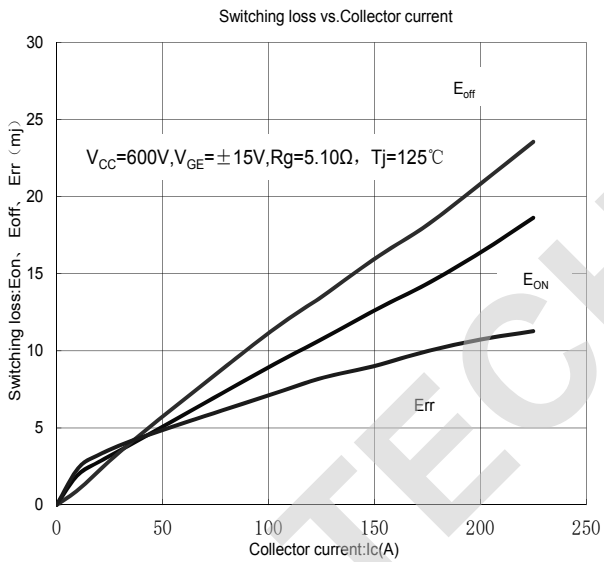
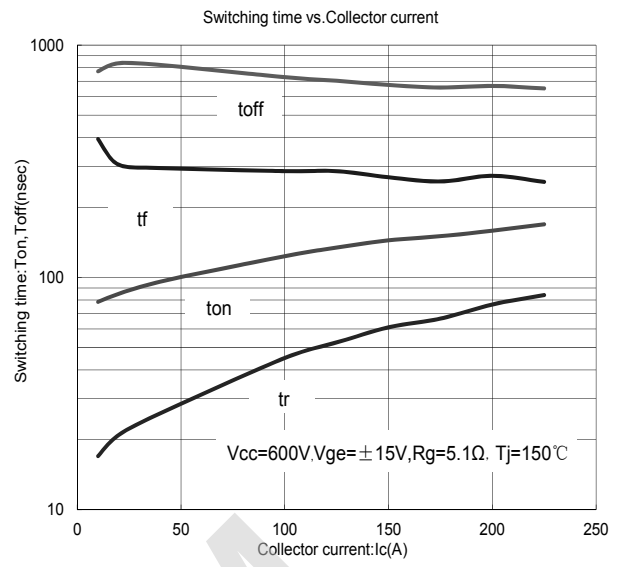
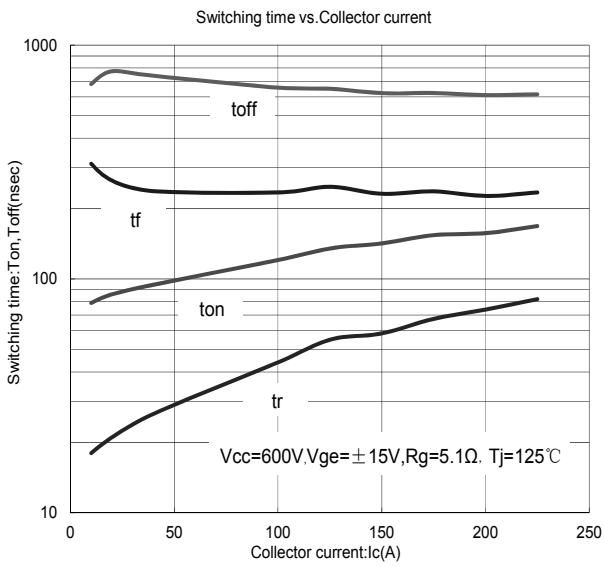
- High speed switching
- Voltage drive
- Low inductance module structure

Typical Applications:

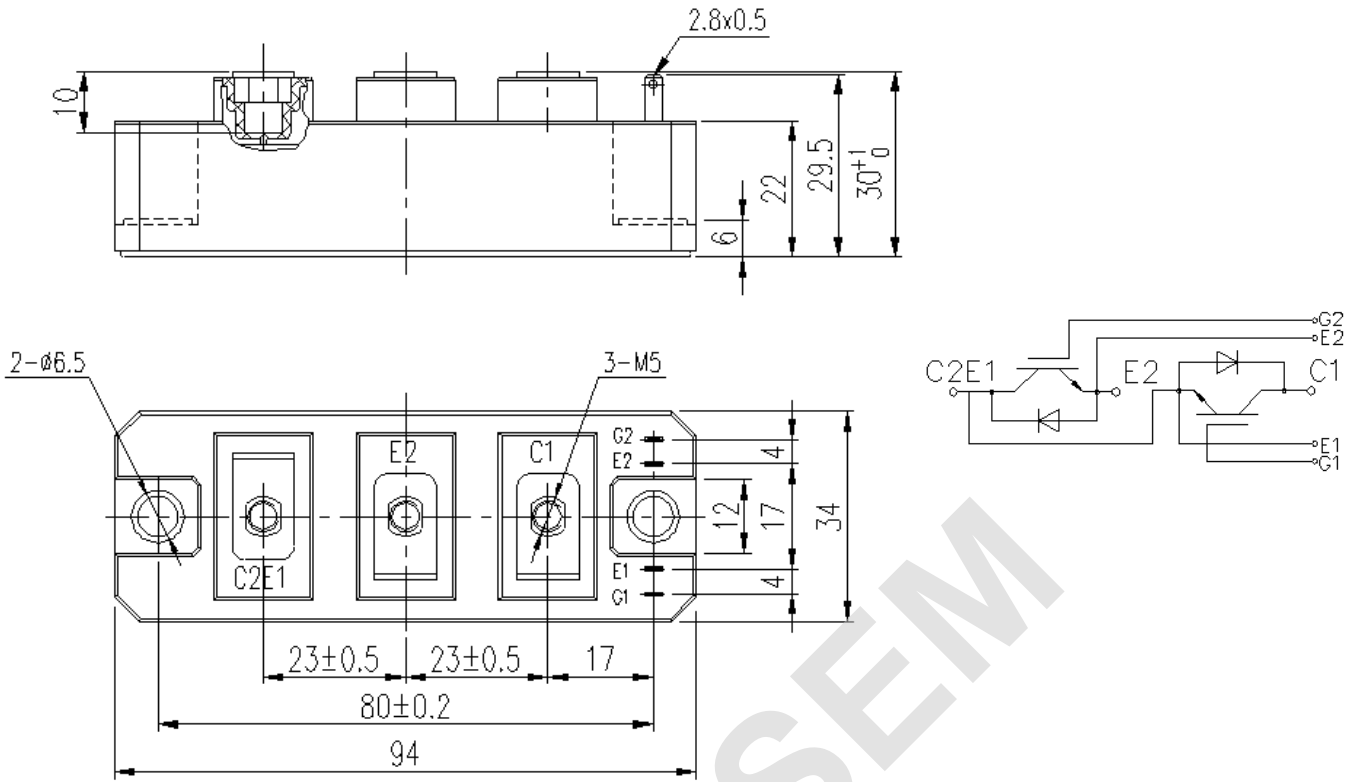
- Inverter for Motor Drive
- Inverter welding machines
- Uninterruptible Power Supply
- Industrial machines

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
V _{CES}	Collector-Emitter voltage	T _j =25°C			1250	V
V _{GES}	Gate-Emitter voltage	T _j =25°C			±30	V
I _c	Collector current	Continuous@ T _c =100°C			150	A
I _{CP}		t _p = 1ms			300	A
P _c	Collector power dissipation	T _j =150°C ,1 device			595	W
T _j	Junction temperature	/			175	°C
T _{stg}	Storage temperature	/	-40		125	°C
V _{iso}	Isolation between terminal and copper base	T _j =25°C ,AC: 1minute	2500			V
Screw torque	Mounting(M6)	/	4.5		6.0	N·m
	Terminals(M5)	/	2.5		4.5	N·m
I _{CES}	Zero gate voltage collector current	T _j =25°C ,V _{CE} =1200V, V _{GE} =0V			1.0	mA
I _{GES}	Gate-Emitter leakage current	T _j =25°C ,V _{CE} =0V, V _{GE} =±20V			±2	µA
V _{GE(th)}	Gate-Emitter threshold voltage	T _j =25°C ,V _{CE} =20V, I _c =150mA	4.5		8.5	V
V _{CE(sat)}	Collector-Emitter saturation voltage	T _j =25°C ,V _{GE} =15V, I _c =150A		1.80	2.40	V
		T _j =125°C ,V _{GE} =15V, I _c =150A		1.95		V
		T _j =150°C ,V _{GE} =15V, I _c =150A		2.25		V
C _{ies}	Input capacitance	T _j =25°C ,V _{CE} =10V, V _{GE} =0V, f=1MHz		12.6		nF
t _{on}	Turn-on time	T _j =150°C ,V _{CC} =600V, I _c =150A, V _{GE} =±15V, R _G =5.1Ω, Inductive load		160		ns
t _r				50		ns
t _{off}				680		ns
t _f				250		ns
t _{sc}	Short circuit withstand time	T _j =150°C ,V _{CC} =720V,V _{GE} =± 15V, R _G =5.1 Ω	10			µs
V _F	Forward on voltage	T _j =25°C ,I _F =150A		2.10	2.60	V
		T _j =125°C ,I _F =150A		2.00		V
		T _j =150°C ,I _F =150A		1.90		V
t _{rr}	Reverse recovery time	T _j =125°C ,I _F =150A		150		ns
		T _j =150°C ,I _F =150A		160		ns
R _{th(j-c)}	Thermal resistance(per chip)	IGBT			0.21	°C/W
		FWD			0.31	°C/W
R _{th(c-f)}	Contact thermal resistance (per module)	With thermal compound		0.05		°C/W
W _t	Weight				155	g
Outline	251H3					





Outline & Circuit Diagram



Unmarked dimensional tolerance: ±0.5mm

TECHSEM